



THE

**LAW SOCIETY**  
OF HONG KONG  
香港律師會

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*From the President*  
會長信箋

To Editor/ Assignment Editor:

### **Response to Media Enquiries about the Use of Technology in Court**

The Law Society has been working closely with the Judiciary to improve efficiency of case management and promote the use of technology in court, especially during the pandemic. Generally speaking, we support lawtech measures that can enhance efficiency and improve access to justice. For example, we have coordinated with the Judiciary Administration to facilitate Law Society members' familiarisation with the Integrated Court Case Management for electronic filing of court-related documents and related electronic payments. Earlier on, the Law Society and the Judiciary Administration co-organised a briefing session with live demonstration to walk court users through on the preparation and use of e-bundles and adducing digitalised evidence in court. Law Society members' familiarisation with various features in the use of e-bundles and adducing digitalised evidence was enhanced through taking part in roleplay in actual courtroom.

To assist small and medium-sized law firms and barristers' chambers to keep up with the Judiciary's development in remote hearings, the Law Society had processed and assessed applications for the LawTech Fund established by the Government, and arranged the disbursement of the funding for law firms and barristers' chambers to procure and upgrade information technology systems and arrange staff to attend lawtech training course.

We look forward to embracing measures that can modernise our judicial infrastructure.

Yours sincerely,

C. M. Chan  
President of The Law Society of Hong Kong  
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